

10 9 8 7 6 5 4 3 2 1

NOTES :

1. MATERIAL :

HOUSING : (a) HIGH TEMP. NYLON ,GLASS FIBER FILLED,UL94V-0, COLOR: BLACK,
(b) POLYESTER , GLASS FIBER FILLED,UL94V-0, COLOR: WHITE,

TERMINAL : PHOSPHOR BRONZE
METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :
CONTACT AREA : (a) GOLD FLASH,
(b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM,
/0.76 MICROMETER MINIMUM.

SOLDER TAIL :
PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
/1.9 MICROMETER MINIMUM.

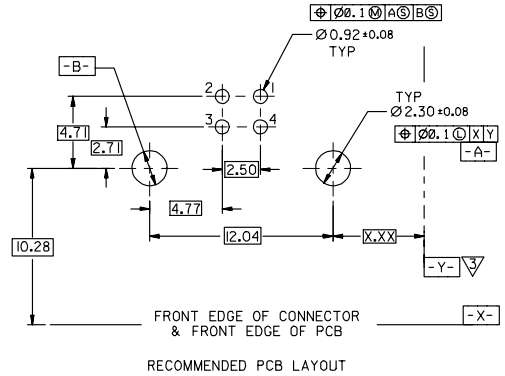
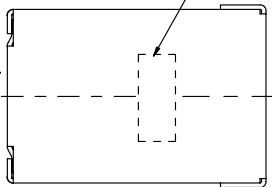
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
/1.27 MICROMETER MINIMUM.

METAL SHELL :
PURE TIN(Sn) , THICKNESS= 50 MICROINCH MINIMUM.
/1.27 MICROMETER MINIMUM.
UNDER PLATE : NICKEL (Ni) , THICKNESS= 50 MICROINCH MINIMUM.
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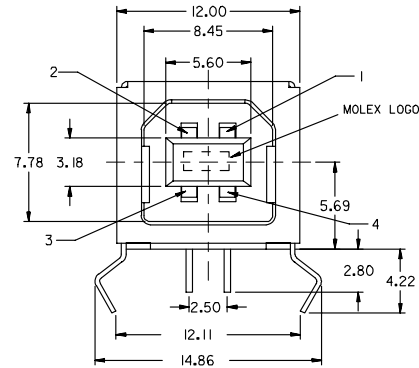
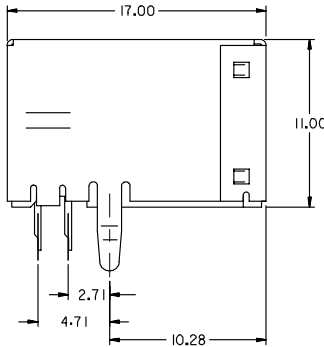
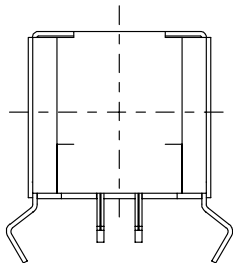
▽ DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

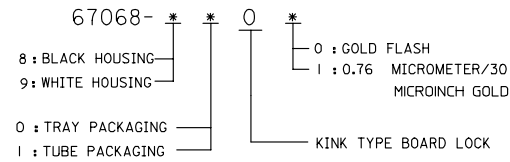
MOLEX ID OF MFG PLANT CODE



FRONT EDGE OF CONNECTOR
& FRONT EDGE OF PCB
RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:



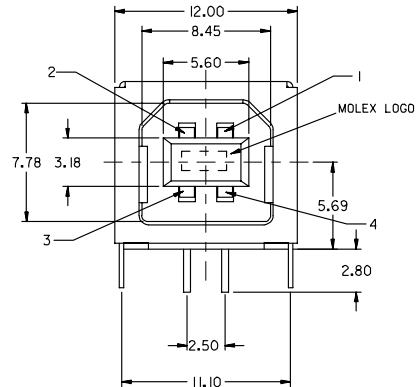
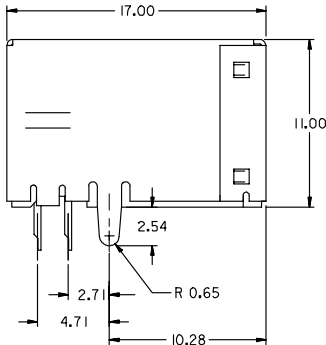
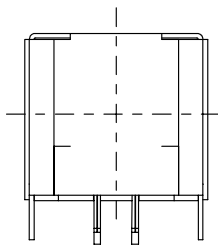
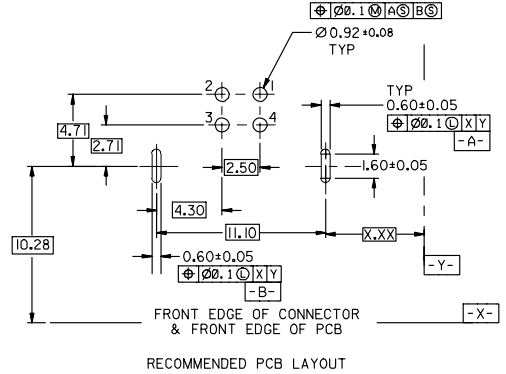
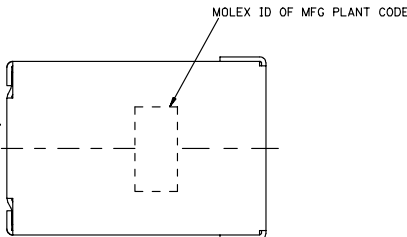
NEW RELEASE EC NO. SH2005-0142 DRAWN: DAVID HU 2004/11/05 CHKD: HARVEY 2004/11/05 APPR: YITAP 2004/11/25	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	1 PLACE ± 0.25 ± ---	ANGULAR ± 3 °	DRAWN BY DAVID HU 2004/11/05
A	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE NOTES	MATERIAL NO.	DOCUMENT NO. SD-67068-003	SHEET NO. 1 OF 4

10 9 8 7 6 5 4 3 2 1

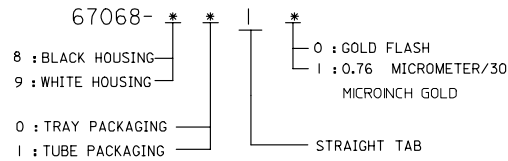
NOTES :
 1. MATERIAL :
 HOUSING : (a) HIGH TEMP. NYLON, CLASS FIBER FILLED, UL94V-0, COLOR: BLACK,
 (b) POLYESTER, CLASS FIBER FILLED, UL94V-0, COLOR: WHITE,
 TERMINAL : PHOSPHOR BRONZE
 METAL SHELL : COPPER ALLOY

2. PLATING :
 TERMINAL :
 CONTACT AREA : (a) GOLD FLASH,
 (b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM,
 /0.76 MICROMETER MINIMUM.
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 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
 /1.9 MICROMETER MINIMUM.
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 /1.27 MICROMETER MINIMUM.
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 /1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
 RECOMMENDED PCB THICKNESS : 1.60±0.05
 4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000



PART NUMBER LEGEND:



NEW RELEASE IEC NO. SH2005-0142 DRWN: DAVID HU 2004/11/05 CHKD: HARRY 2004/11/05 APPR: YITAP 2004/11/25	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION															
	$\nabla=0$ $\nabla=0$	<table border="1"> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.25</td> <td>± --- 2004/11/05</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.25</td> <td>± ---</td> </tr> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.25	± --- 2004/11/05	1 PLACE	± 0.25	± ---	MM ONLY	4:1	METRIC	
		mm	INCH																		
	4 PLACES	± ---	± ---																		
3 PLACES	± ---	± ---																			
2 PLACES	± 0.25	± --- 2004/11/05																			
1 PLACE	± 0.25	± ---																			
DESCRIPTION	ANGULAR ± 3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY DATE DAVID HU 2004/11/05 CHECKED BY DATE HARRY 2004/11/05 APPROVED BY DATE YITAP	TITLE USB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)																		
REV			MATERIAL NO. SEE NOTES	DOCUMENT NO. SD-67068-003	MOLEX INCORPORATED	SHEET NO. 2															

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NOTES :

1. MATERIAL :

HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE
 METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :
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 (b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM,
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 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM ,
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UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM,
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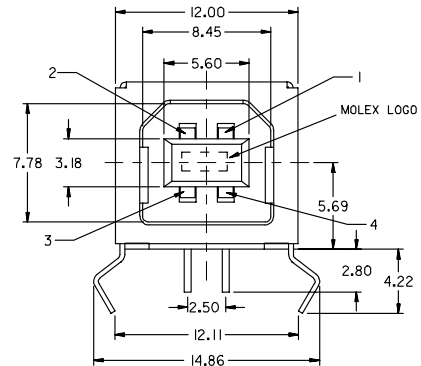
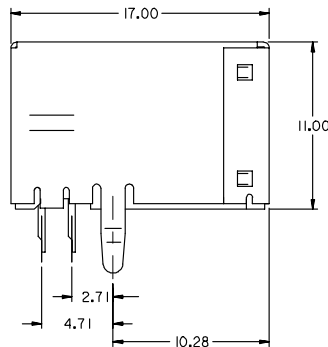
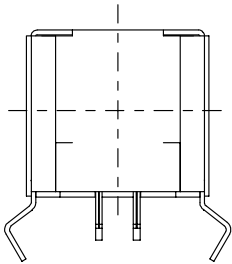
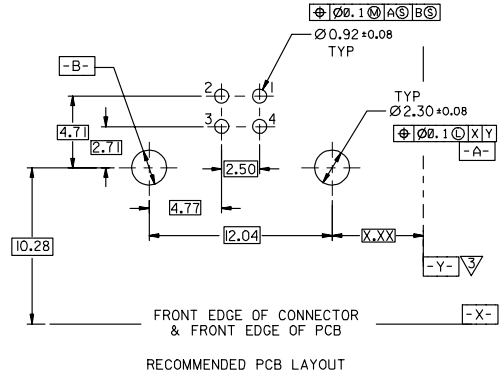
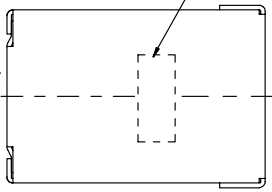
METAL SHELL :
 PURE TIN(Sn), THICKNESS= 50 MICROINCH MINIMUM,
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UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM,
 /1.27 MICROMETER MINIMUM.

DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
 RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



PART NUMBER LEGEND:

67068- 7041

				MATERIAL : SEE NOTES		MOLEX TAIWAN LTD.	
				FINISH : SEE NOTES		SHEET 3 OF 4	
				WIRE RANGE :		GENERAL TOLERANCES	
				INS. RANGE :		ANGLE : ± 3° DIM : ± .25/.010	
A NEW RELEASE FOR LEAD-FREE		DAVID HU 2004/11/5		DRAWN BY 2004/11/5		CHK'D BY	
LTR		REVISION RECORD		ECN		DR	
DATE		DAVID HU		APPR'D BY		SCALE 4 : 1	
REVISE ONLY ON CAD SYSTEM				TITLE : HIGH TEMP USB B TYPE CONNECTOR		KINK TYPE BOARD LOCK (LEAD-FREE)	

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX (FEM) AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

MXT, Sg - 13

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DO NOT SCALE DRAWING

DO NOT SCALE DRAWING

DO NOT SCALE DRAWING

ENG. NO SDA-67068-0000

EDP NO.

SIMILAR ITEM

CAD FILE : _S6706802_

DO NOT SCALE DRAWING

NOTES :

1. MATERIAL :

HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE
METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL : (a) GOLD FLASH.
CONTACT AREA : (a) GOLD FLASH.
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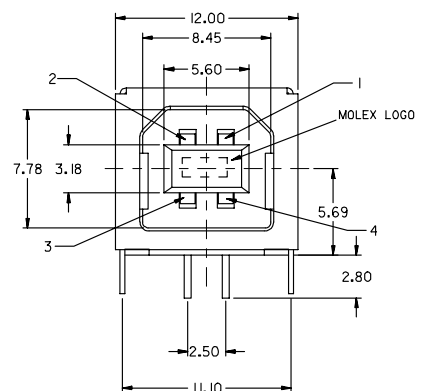
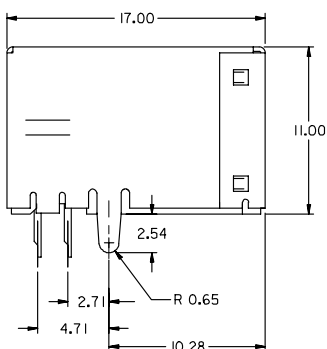
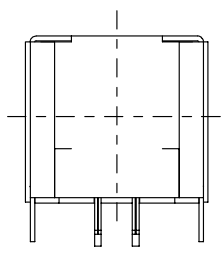
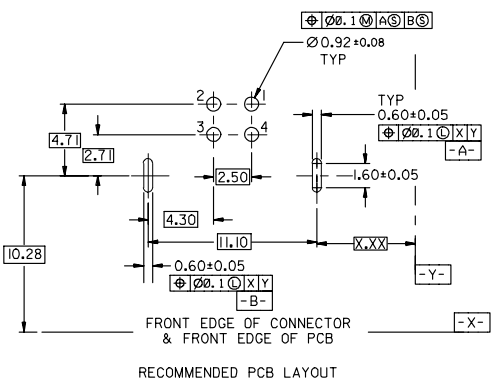
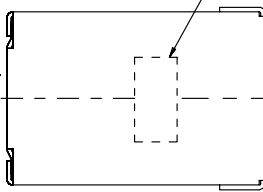
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
/1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER

RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



PART NUMBER LEGEND:

67068- 7051

				MATERIAL : SEE NOTES		MOLEX TAIWAN LTD.	
				FINISH : SEE NOTES		SHEET 4 OF 4	
				WIRE RANGE :		GENERAL TOLERANCES	
				INS. RANGE :		ANGLE : ± 3° DIM : ± .25/.010	
A NEW RELEASE FOR LEAD-FREE				DAVID HJ 2006/11/5		ENG. NO.: SD-67068-003	
LTR REVISION RECORD				ECN DR DATE		DRAWN BY 2004/11/5	
				DAVID HJ		CHK'D BY	
REVISE ONLY ON CAD SYSTEM				APPR'D BY		SCALE 4 : 1	
						TITLE : HIGH TEMPSUB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)	
						REV A	

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX (FEMLE) AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION MXT, Sg - 13